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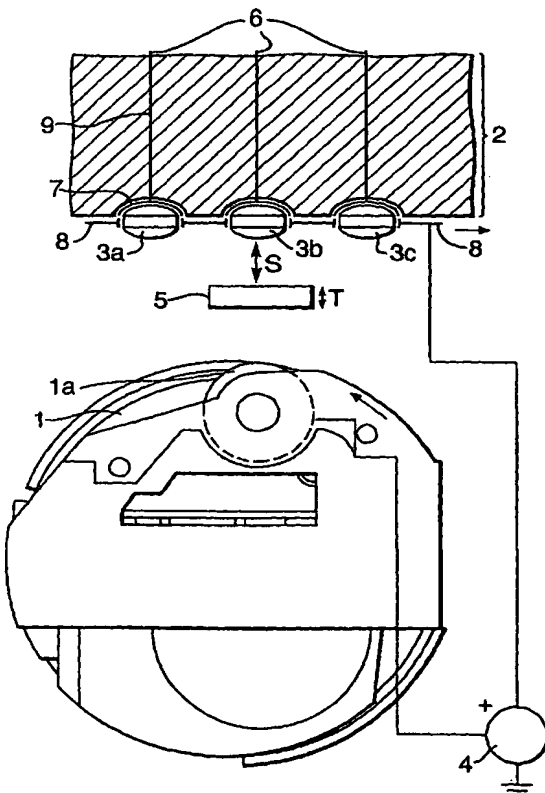
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(54) Title: METHOD AND APPARATUS FOR APPLYING POWDER IN A PATTERN TO A SUBSTRATE



(57) Abstract: A method and apparatus for providing a pattern on a solid dosage form, in which powder material is applied in a pattern to a substrate (3). A mask (5) having an aperture is provided between a source (1) of the powder material and the substrate (3) and the powder material is applied to the substrate through the mask (5). Relative movement of the substrate with respect to the source (1) of powder material is effected during the pattern application process.